

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Hong-Sik Jeong et al.

Confirmation No.: 5150

Serial No.: 10/008,700

Group Art Unit: 2818

Filed: December 7, 2001

Examiner: Chuong A. Luu

For: METHODS OF MANUFACTURING INTEGRATED CIRCUIT DEVICES
HAVING AN ENCAPSULATED INSULATION LAYER

Date: June 11, 2007

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Sir:

Applicants provide the present Amendment to address the issues raised in the Official Action mailed February 14, 2007.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 6 of this paper.

It is not believed that an extension of time and/or additional fee(s), including fees for net addition of claims, are required, beyond those that may otherwise be provided for in documents accompanying this paper. In the event, however, that an extension of time is necessary to allow consideration of this paper, such an extension is hereby petitioned under 37 C.F.R. §1.136(a). Any additional fees believed to be due in connection with this paper may be charged to our Deposit Account No. 50-0220.